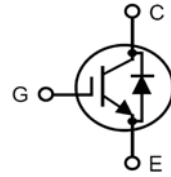


**XPT™ 600V IGBT
GenX3™ w/ Diode**
IXXH30N60B3D1


$$V_{CES} = 600V$$

$$I_{C110} = 30A$$

$$V_{CE(sat)} \leq 1.85V$$

$$t_{fi(typ)} = 125ns$$

 Extreme Light Punch Through
IGBT for 5-30 kHz Switching

| Symbol | Test Conditions | Maximum Ratings | |
|-------------------------------|---|--|------------|
| V_{CES} | $T_J = 25^\circ C$ to $175^\circ C$ | 600 | V |
| V_{CGR} | $T_J = 25^\circ C$ to $175^\circ C$, $R_{GE} = 1M\Omega$ | 600 | V |
| V_{GES} | Continuous | ± 20 | V |
| V_{GEM} | Transient | ± 30 | V |
| I_{C25} | $T_C = 25^\circ C$ | 60 | A |
| I_{C110} | $T_C = 110^\circ C$ | 30 | A |
| I_{F110} | $T_C = 110^\circ C$ | 30 | A |
| I_{CM} | $T_C = 25^\circ C$, 1ms | 115 | A |
| I_A | $T_C = 25^\circ C$ | 20 | A |
| E_{AS} | $T_C = 25^\circ C$ | 250 | mJ |
| SSOA (RBSOA) | $V_{GE} = 15V$, $T_{VJ} = 150^\circ C$, $R_G = 10\Omega$ Clamped Inductive Load | $I_{CM} = 48$ @ $V_{CE} \leq V_{CES}$ | A |
| t_{sc} (SCSOA) | $V_{GE} = 15V$, $V_{CE} = 360V$, $T_J = 150^\circ C$ $R_G = 82\Omega$, Non Repetitive | 10 | μs |
| P_C | $T_C = 25^\circ C$ | 270 | W |
| T_J | | -55 ... +175 | $^\circ C$ |
| T_{JM} | | 175 | $^\circ C$ |
| T_{stg} | | -55 ... +175 | $^\circ C$ |
| T_L | Maximum Lead Temperature for Soldering | 300 | $^\circ C$ |
| T_{SOLD} | 1.6 mm (0.062in.) from Case for 10s | 260 | $^\circ C$ |
| M_d | Mounting Torque | 1.13/10 | Nm/lb.in. |
| Weight | | 6 | g |

TO-247 AD


G = Gate C = Collector
E = Emitter Tab = Collector

Features

- Optimized for 5-30kHz Switching
- Square RBSOA
- Anti-Parallel Ultra Fast Diode
- Avalanche Capability
- Short Circuit Capability
- International Standard Package

Advantages

- High Power Density
- $175^\circ C$ Rated
- Extremely Rugged
- Low Gate Drive Requirement

Applications

- Power Inverters
- UPS
- Motor Drives
- SMPS
- PFC Circuits
- Battery Chargers
- Welding Machines
- Lamp Ballasts

| Symbol | Test Conditions ($T_J = 25^\circ C$, Unless Otherwise Specified) | Characteristic Values | | |
|---------------|---|-----------------------|--------------|---------------------|
| | | Min. | Typ. | Max. |
| BV_{CES} | $I_C = 250\mu A$, $V_{GE} = 0V$ | 600 | | V |
| $V_{GE(th)}$ | $I_C = 250\mu A$, $V_{CE} = V_{GE}$ | 3.0 | | 5.5 V |
| I_{CES} | $V_{CE} = V_{CES}$, $V_{GE} = 0V$ $T_J = 150^\circ C$ | | | 100 μA 1 mA |
| I_{GES} | $V_{CE} = 0V$, $V_{GE} = \pm 20V$ | | | ± 100 nA |
| $V_{CE(sat)}$ | $I_C = 24A$, $V_{GE} = 15V$, Note 1 $T_J = 150^\circ C$ | | 1.66 1.97 | 1.85 V V |

| Symbol Test Conditions ($T_J = 25^\circ\text{C}$ Unless Otherwise Specified) | | Characteristic Values | | |
|--|--|-----------------------|------|---------------------------|
| | | Min. | Typ. | Max. |
| g_{fs} | $I_C = 24\text{A}, V_{CE} = 10\text{V}, \text{Note 1}$ | 8 | 14 | S |
| C_{ies} | $V_{CE} = 25\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$ | | 1185 | pF |
| C_{oes} | | | 137 | pF |
| C_{res} | | | 25 | pF |
| $Q_{g(on)}$ | $I_C = 24\text{A}, V_{GE} = 15\text{V}, V_{CE} = 0.5 \cdot V_{CES}$ | | 39 | nC |
| Q_{ge} | | | 9 | nC |
| Q_{gc} | | | 17 | nC |
| $t_{d(on)}$ | Inductive load, $T_J = 25^\circ\text{C}$ $I_C = 24\text{A}, V_{GE} = 15\text{V}$ $V_{CE} = 400\text{V}, R_G = 10\Omega$ Note 2 | | 23 | ns |
| t_{ri} | | | 36 | ns |
| E_{on} | | | 0.55 | mJ |
| $t_{d(off)}$ | | | 97 | 150 ns |
| t_{fi} | | | 125 | ns |
| E_{off} | | | 0.50 | 0.80 mJ |
| $t_{d(on)}$ | Inductive load, $T_J = 150^\circ\text{C}$ $I_C = 24\text{A}, V_{GE} = 15\text{V}$ $V_{CE} = 400\text{V}, R_G = 10\Omega$ Note 2 | | 23 | ns |
| t_{ri} | | | 34 | ns |
| E_{on} | | | 1.10 | mJ |
| $t_{d(off)}$ | | | 112 | ns |
| t_{fi} | | | 180 | ns |
| E_{off} | | | 0.70 | mJ |
| R_{thJC} | | | 0.55 | $^\circ\text{C}/\text{W}$ |
| R_{thCS} | | 0.21 | | $^\circ\text{C}/\text{W}$ |

TO-247 (IXXH) Outline



Terminals: 1 - Gate 2 - Collector
3 - Emitter

| Dim. | Millimeter | | Inches | |
|----------------|------------|-------|--------|-------|
| | Min. | Max. | Min. | Max. |
| A | 4.7 | 5.3 | .185 | .209 |
| A ₁ | 2.2 | 2.54 | .087 | .102 |
| A ₂ | 2.2 | 2.6 | .059 | .098 |
| b | 1.0 | 1.4 | .040 | .055 |
| b ₁ | 1.65 | 2.13 | .065 | .084 |
| b ₂ | 2.87 | 3.12 | .113 | .123 |
| C | .4 | .8 | .016 | .031 |
| D | 20.80 | 21.46 | .819 | .845 |
| E | 15.75 | 16.26 | .610 | .640 |
| e | 5.20 | 5.72 | 0.205 | 0.225 |
| L | 19.81 | 20.32 | .780 | .800 |
| L1 | | 4.50 | | .177 |
| ∅P | 3.55 | 3.65 | .140 | .144 |
| Q | 5.89 | 6.40 | 0.232 | 0.252 |
| R | 4.32 | 5.49 | .170 | .216 |
| S | 6.15 | BSC | 242 | BSC |

Reverse Diode (FRED)

| Symbol Test Conditions ($T_J = 25^\circ\text{C}$ Unless Otherwise Specified) | | Characteristic Values | | |
|--|---|-----------------------|---------------------------|-------------------------------|
| | | Min. | Typ. | Max. |
| V_F | $I_F = 30\text{A}, V_{GE} = 0\text{V}, \text{Note 1}$ | | | 2.7 V |
| | | | $T_J = 150^\circ\text{C}$ | 1.6 V |
| I_{RM} | $I_F = 30\text{A}, V_{GE} = 0\text{V}, -di_F/dt = 100\text{A}/\mu\text{s},$ | | $T_J = 100^\circ\text{C}$ | 4 A |
| t_{rr} | $V_R = 100\text{V}$ | | $T_J = 100^\circ\text{C}$ | 100 ns |
| | $I_F = 1\text{A}, V_{GE} = 0\text{V}, -di_F/dt = 100\text{A}/\mu\text{s}, V_R = 30\text{V}$ | | | 25 ns |
| R_{thJC} | | | | 0.9 $^\circ\text{C}/\text{W}$ |

Notes:

1. Pulse test, $t \leq 300\mu\text{s}$, duty cycle, $d \leq 2\%$.
2. Switching times & energy losses may increase for higher V_{CE} (clamp), T_J or R_G .

PRELIMINARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from data gathered during objective characterizations of preliminary engineering lots; but also may yet contain some information supplied during a pre-production design evaluation. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

| | | | | | | | | | | |
|--|-----------|-----------|-----------|-----------|--------------|--------------|--------------|--------------|--------------|-------------|
| IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: | 4,835,592 | 4,931,844 | 5,049,961 | 5,237,481 | 6,162,665 | 6,404,065 B1 | 6,683,344 | 6,727,585 | 7,005,734 B2 | 7,157,338B2 |
| | 4,860,072 | 5,017,508 | 5,063,307 | 5,381,025 | 6,259,123 B1 | 6,534,343 | 6,710,405 B2 | 6,759,692 | 7,063,975 B2 | |
| | 4,881,106 | 5,034,796 | 5,187,117 | 5,486,715 | 6,306,728 B1 | 6,583,505 | 6,710,463 | 6,771,478 B2 | 7,071,537 | |

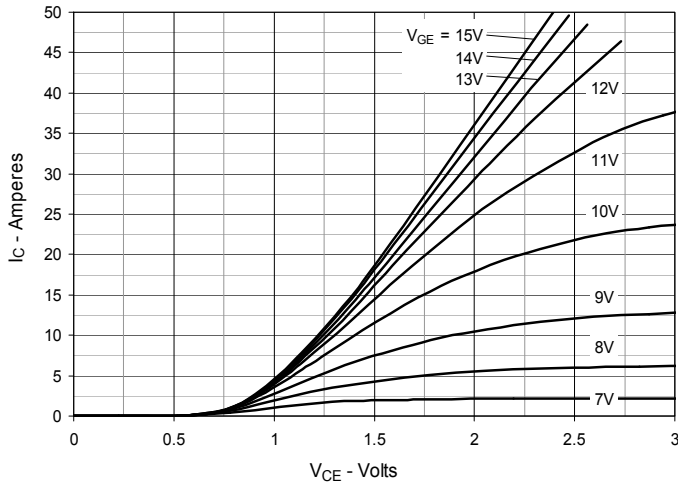
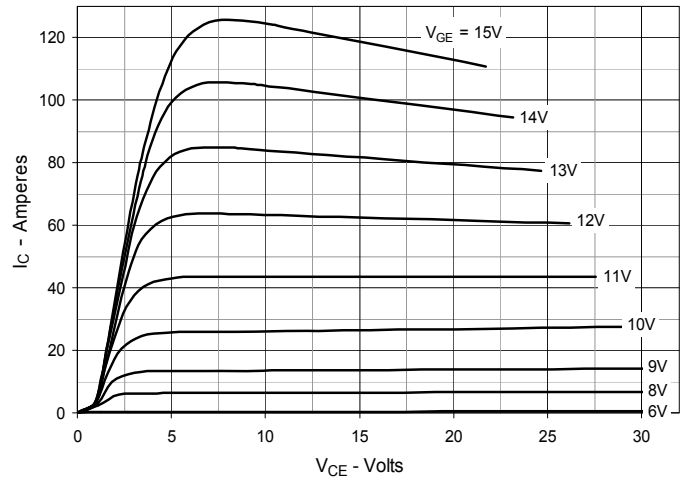
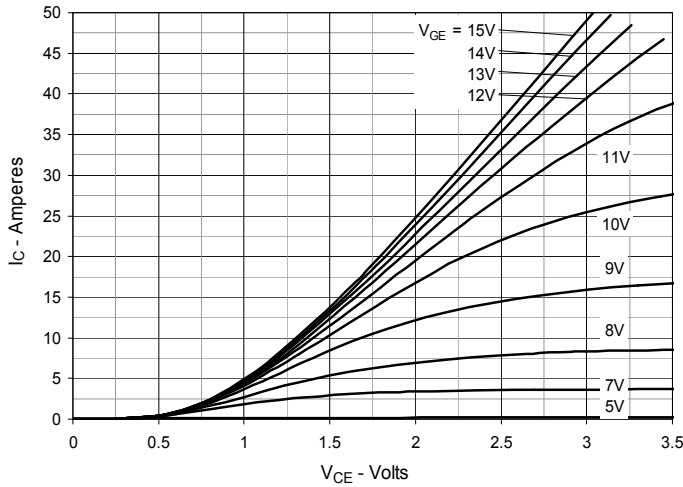
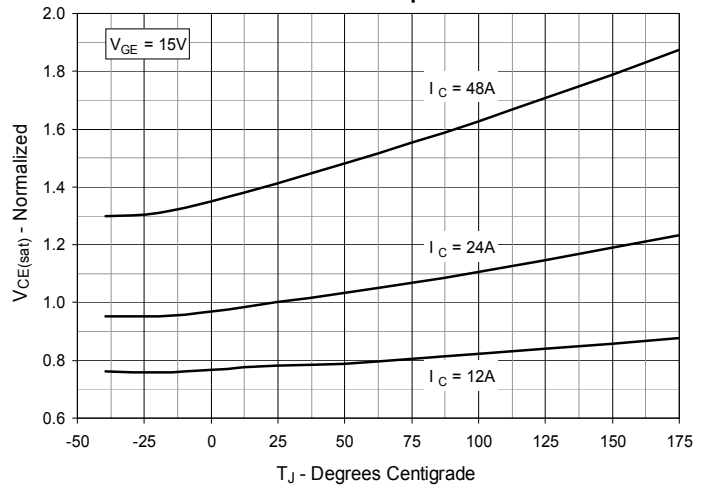
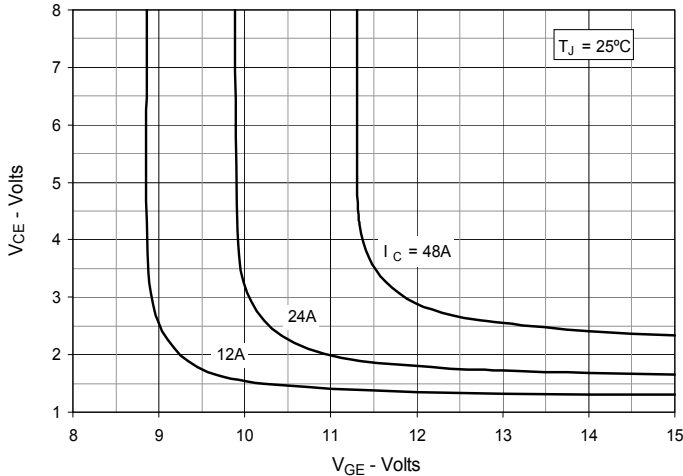
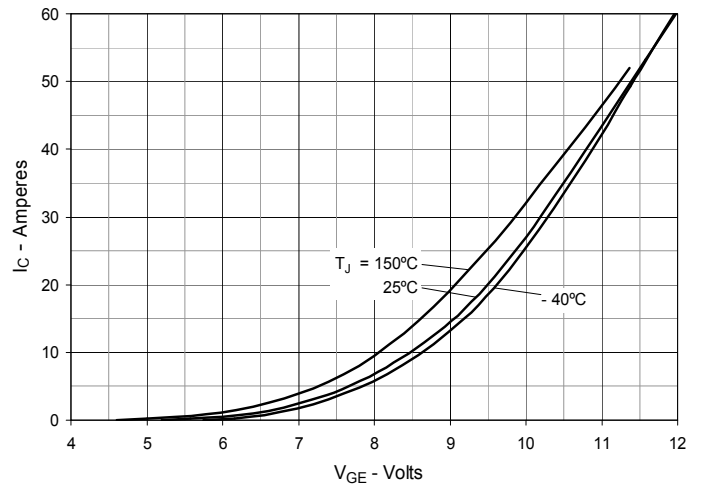
Fig. 1. Output Characteristics @ $T_J = 25^\circ\text{C}$

Fig. 2. Extended Output Characteristics @ $T_J = 25^\circ\text{C}$

Fig. 3. Output Characteristics @ $T_J = 150^\circ\text{C}$

Fig. 4. Dependence of $V_{CE(sat)}$ on Junction Temperature

Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage

Fig. 6. Input Admittance


Fig. 7. Transconductance

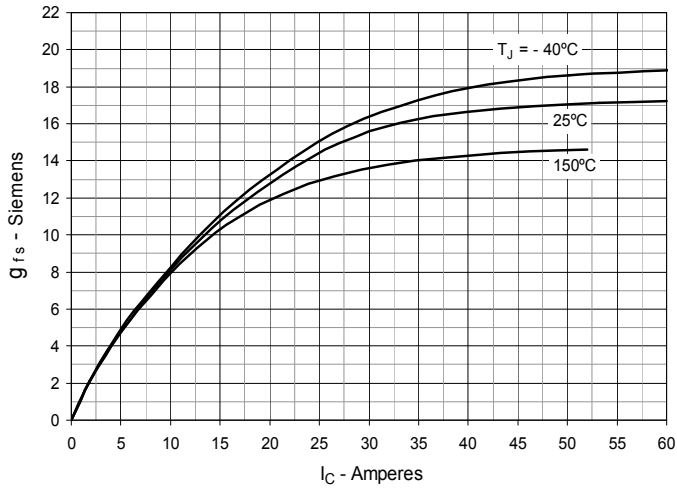


Fig. 8. Gate Charge

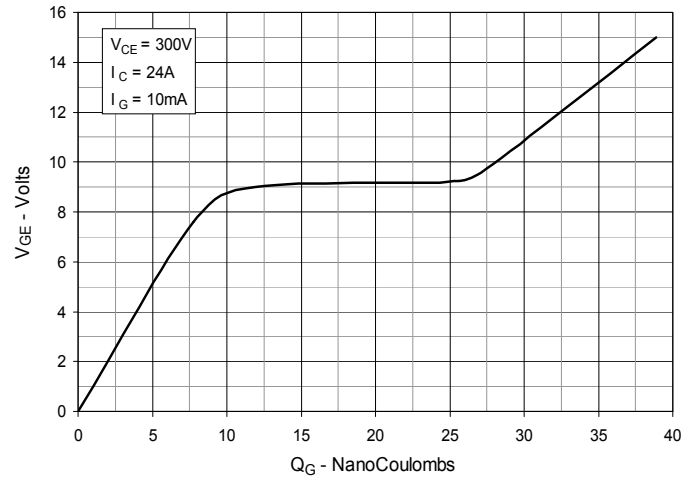


Fig. 9. Capacitance

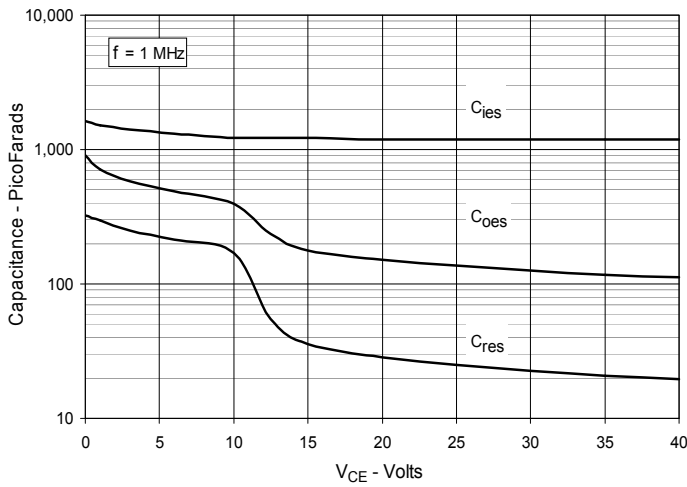


Fig. 10. Reverse-Bias Safe Operating Area

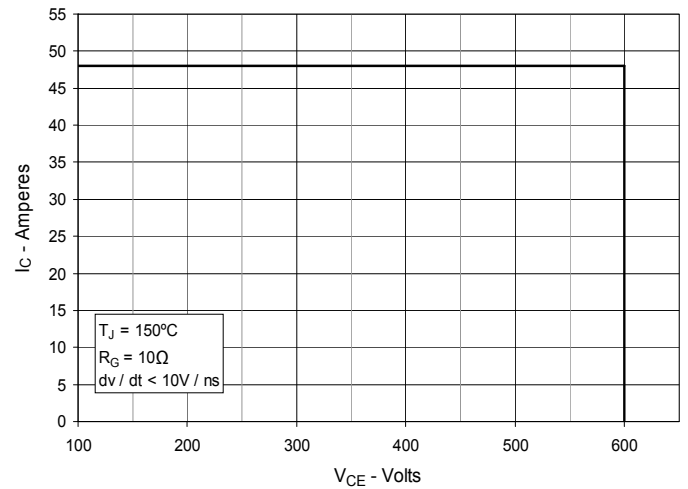


Fig. 11. Forward-Bias Safe Operating Area

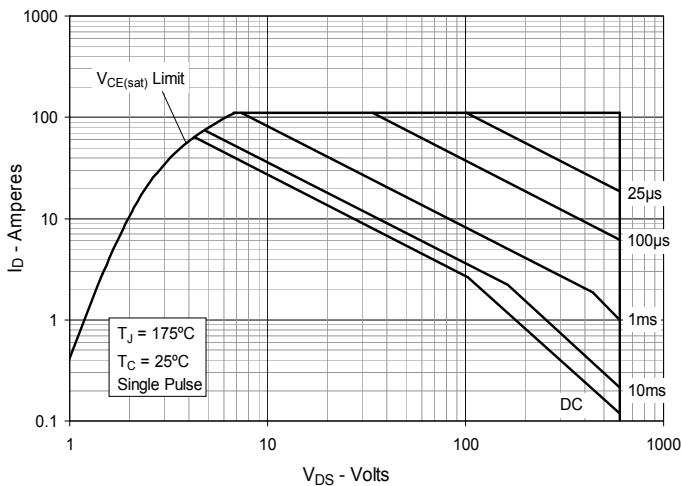


Fig. 12. Maximum Transient Thermal Impedance

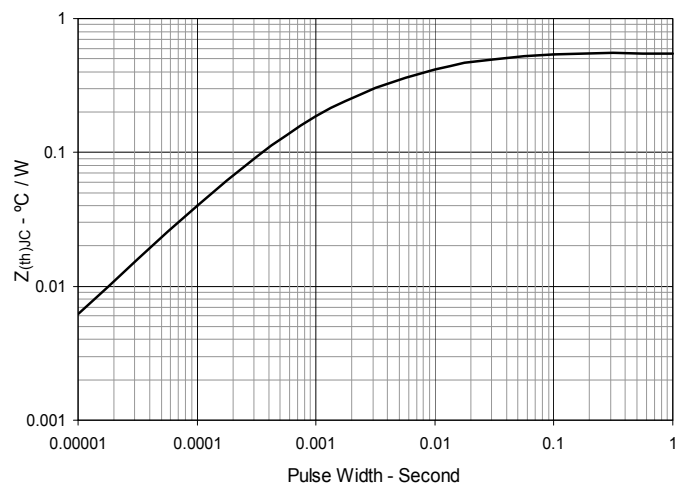


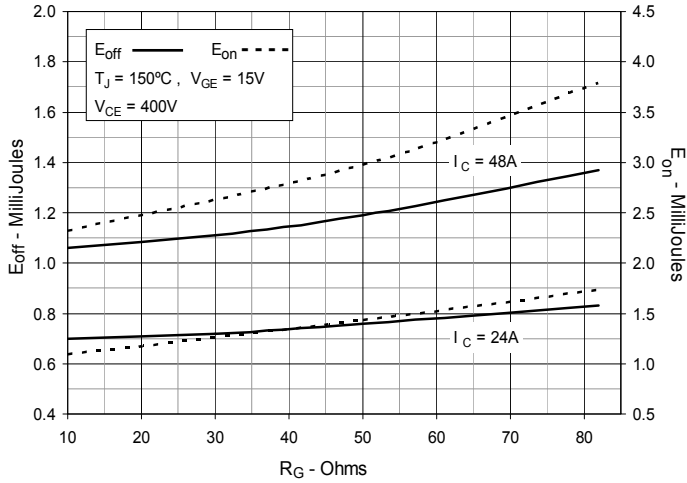
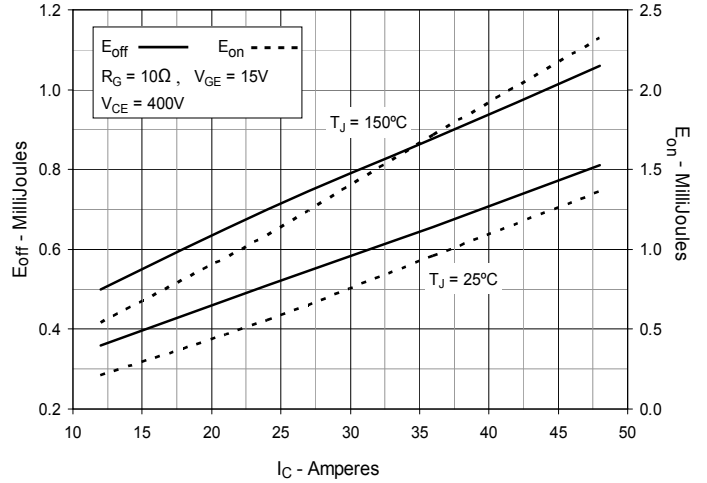
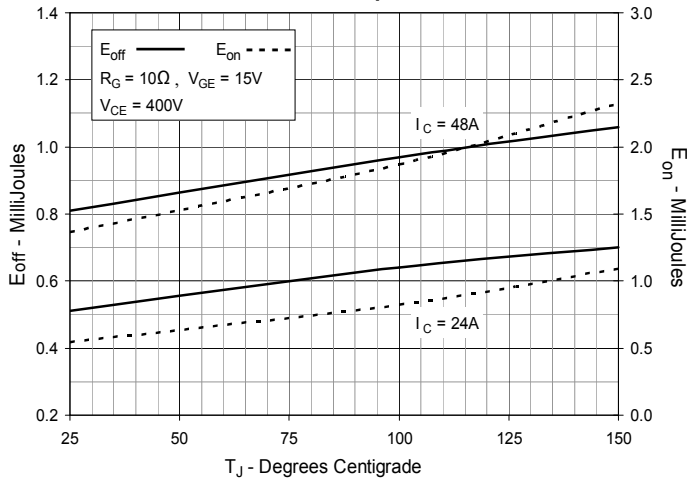
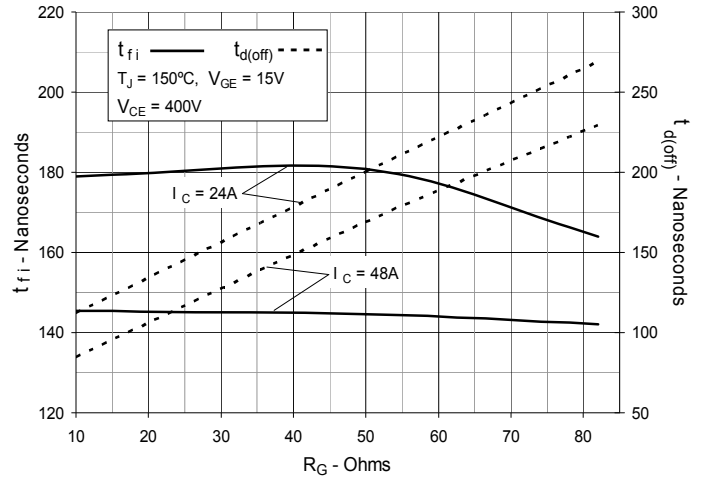
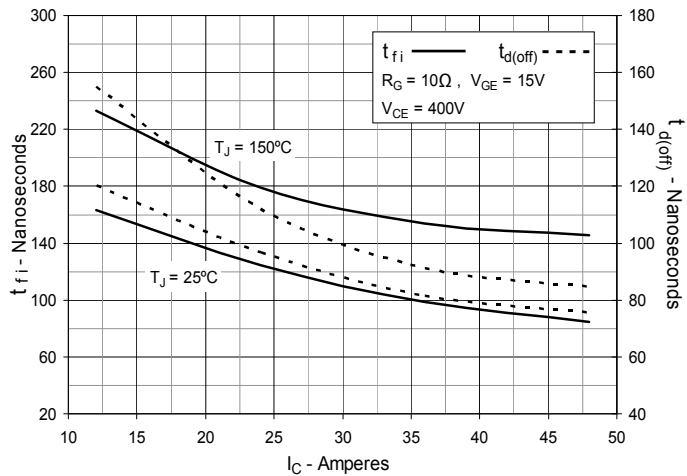
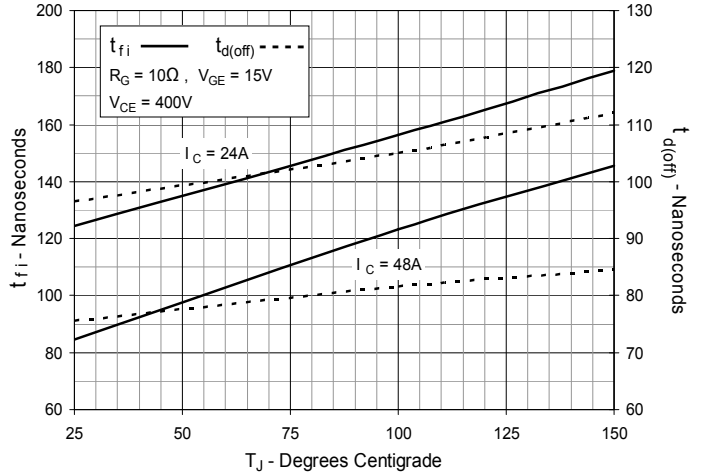
Fig. 13. Inductive Switching Energy Loss vs. Gate Resistance

Fig. 14. Inductive Switching Energy Loss vs. Collector Current

Fig. 15. Inductive Switching Energy Loss vs. Junction Temperature

Fig. 16. Inductive Turn-off Switching Times vs. Gate Resistance

Fig. 17. Inductive Turn-off Switching Times vs. Collector Current

Fig. 18. Inductive Turn-off Switching Times vs. Junction Temperature


Fig. 19. Inductive Turn-on Switching Times vs. Gate Resistance

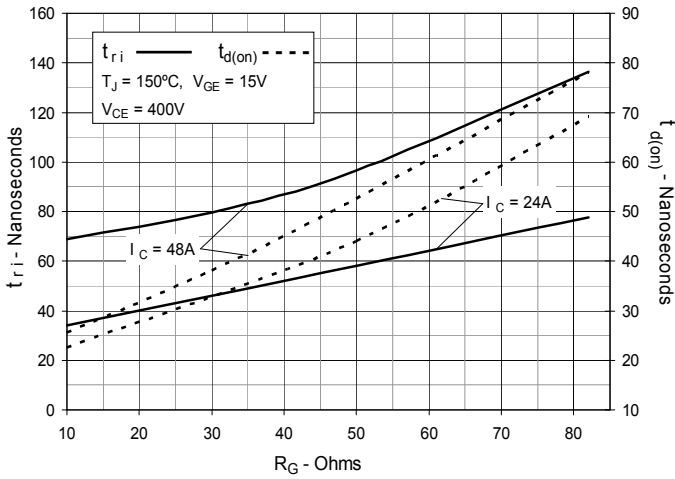


Fig. 20. Inductive Turn-on Switching Times vs. Collector Current

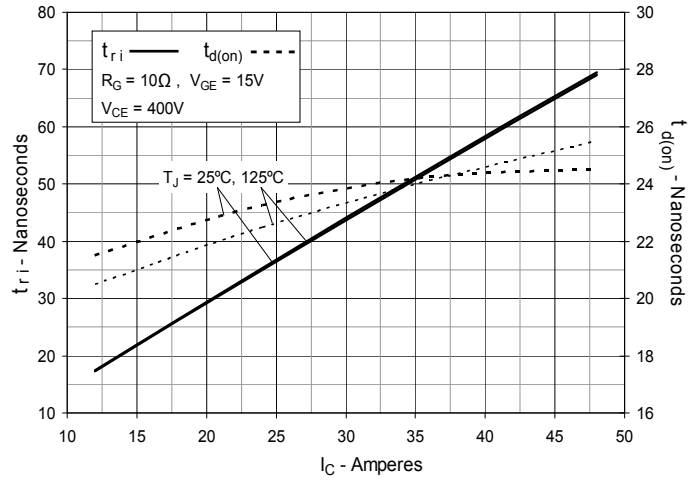
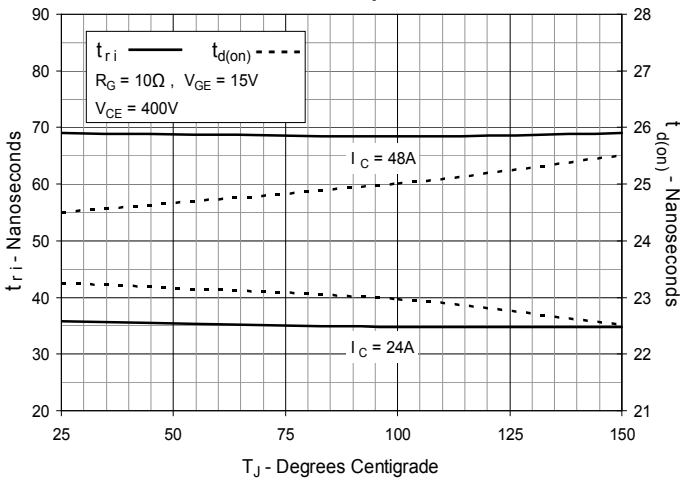


Fig. 21. Inductive Turn-on Switching Times vs. Junction Temperature



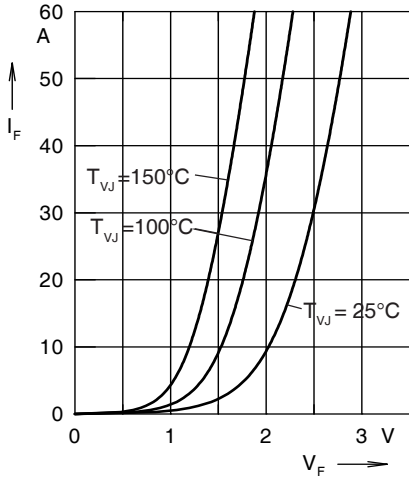


Fig. 22. Forward Current I_F Versus V_F

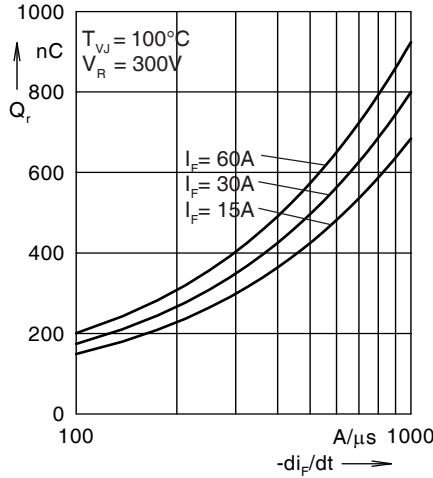


Fig. 23. Reverse Recovery Charge Q_r Versus $-di_F/dt$

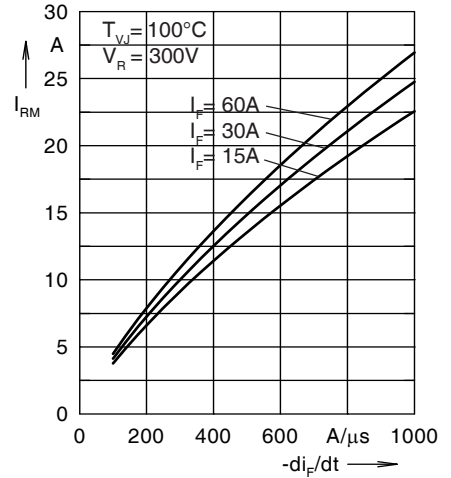


Fig. 24. Peak Reverse Current I_{RM} Versus $-di_F/dt$

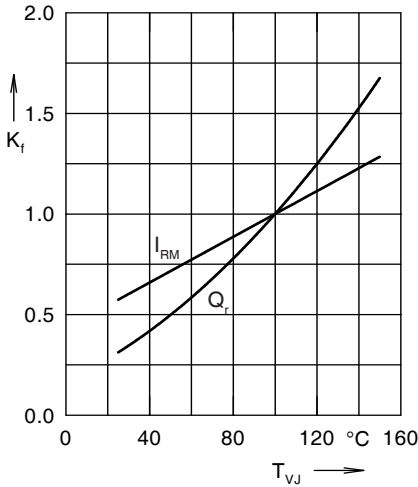


Fig. 25. Dynamic Parameters Q_r , I_{RM} Versus T_{VJ}

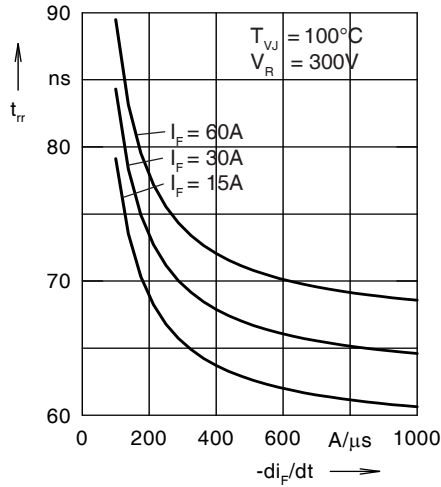


Fig. 26. Recovery Time t_{rr} Versus $-di_F/dt$

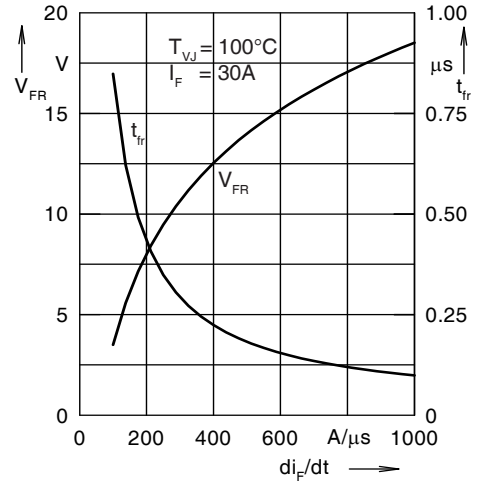


Fig. 28. Peak Forward Voltage V_{FR} and t_{fr} Versus di_F/dt

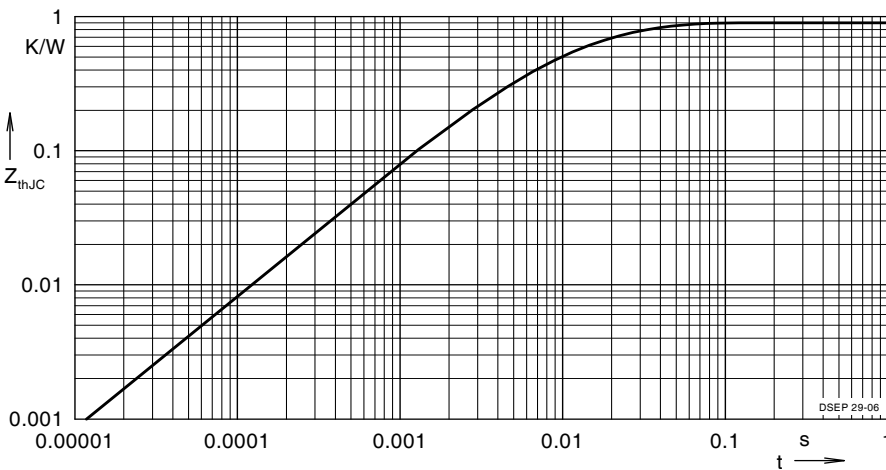


Fig. 28. Transient Thermal Resistance Junction to Case